

1989 Index

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This index covers all items — papers, correspondence, reviews, etc. — that appeared in this periodical during 1989, and items from previous years that were commented upon or corrected in 1989.

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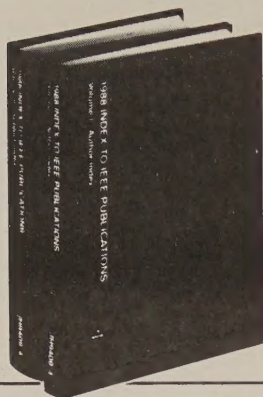
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ULSI (ultra-large-scale integration); cf. Fabrication, VLSI

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VLSI (very-large-scale integration); cf. Fabrication, VLSI

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